Central™
Semiconductor Corp.
145 Adams Avenue
Hauppauge, New York 11788 USA
Tel: (631) 435-1110 • Fax: (631) 435-1824
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PCN #: 105

Notification Date:
24 November 2004

Process Change Notice

Parts Affected:
Small signal discrete semiconductors, wafers, and die in chip form.

Extent of Change:
Reduction in the standard die thickness of discrete, small signal wafers from 9.0 mils (230μm) ± 0.6 mils (15μm), to 7.1 mils (180μm) ± 0.8 mils (20μm).

Reason for Change:
To accommodate assemblies of surface mount, epoxy molded packages, with very low package height (<1.0mm).

Effect of Change:
This change does not affect the electrical characteristics of any device.

Effective Date of Change:
Existing inventory will be shipped until depleted.

Sample Availability:
Please contact Salesperson or Manufacturer's Representative.

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Chip Process Part Numbers Affected

Standard Wafer Process Number 9.0 mils thickness (230µm)	New Wafer Process Number 7.1 mils thickness (180µm)
CPD48	CPD48V
CPD76	CPD76V
CPD78	CPD78V
CPD80	CPD80V
CPD83	CPD83V
CPD88	CPD88V
CPD91	CPD91V
CPD92	CPD92V
CPD96	CPD96V
CP188	CP188V
CP191	CP191V
CP192	CP192V
CP305	CP305V
CP307	CP307V
CP309	CP309V
CP310	CP310V
CP314	CP314V
CP315	CP315V
CP316	CP316V
CP317	CP317V
CP318	CP318V
CP324	CP324V
CP355	CP355V
CP392	CP392V
CP588	CP588V
CP591	CP591V
CP592	CP592V
CP705	CP705V
CP709	CP709V
CP710	CP710V
CP716	CP716V
CP720	CP720V
CP734	CP734V
CP755	CP755V
CP767	CP767V
CP792	CP792V